Processing Guides for WONDERLITE® PC-115U

A. Pre-drying  120°C x 4 hrs
   depending on  a) Humidity
                b) Storage conditions
                c) Dryer’s performance

B. Barrel Setting Profile

<table>
<thead>
<tr>
<th>Grade / Application</th>
<th>Nozzle</th>
<th>Compression zone</th>
<th>Feeding zone</th>
<th>Mold Temperature *</th>
</tr>
</thead>
<tbody>
<tr>
<td>PC-115U</td>
<td>max.  {°C}</td>
<td>300</td>
<td>310</td>
<td>300</td>
</tr>
<tr>
<td></td>
<td>min.  {°C}</td>
<td>250</td>
<td>250</td>
<td>230</td>
</tr>
</tbody>
</table>

* varying with  a) Thickness of molded articles
               b) Cooling system design
               c) Gate and runner system

NOTE:
1. Keep the resin from dust and contamination during handling and production.
2. Do not retain the hot melt at the barrel for a long time between injection cycles.
3. Temperature setting of manifold system should not exceed 330°C to avoid melt from degrading.

Purging:
Heat decomposing resins are not recommended for purging the residual WONDERLITE® and WONDERLOY® in barrel of injection machine and extruder. Polyethylene and polypropylene are the most commonly used heat stable resins for purging purpose.

For further information, please contact your local agent or fax to CHIMEI-ASAHI Technical Services Dept. at 886-6-2667983/2667984

WONDERLITE – PC · WONDERLOY – PC/ABS